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Docket No.: M-11590 US

January 2, 2002

Box Patent Application
Commissioner For Patents
Washington, D. C. 20231

Enclosed herewith for filing is a patent application, as follows:

Inventor(s): Nam, Shibaek; Jeon, Oseob; Heo, Chulho
 Title: Semiconductor Device Having Multi-Chip Package Structure

X Return Receipt Postcard
X This Transmittal Letter (in duplicate)
11 page(s) Specification (not including claims)
8 page(s) Claims
1 page Abstract
4 Sheet(s) of Drawings (For Figs. 1, 2, 3, 4, 5 and 6)
2 page(s) Declaration For Patent Application and Power of Attorney
1 page(s) Recordation Form Cover Sheet (in duplicate)
2 page(s) Assignment

CLAIMS AS FILED

For	Number			Number		Rate		Basic Fee
	<u>Filed</u>			<u>Extra</u>				
Total Claims	60	-20	=	40	x	\$18.00	=	\$ 740.00
								\$ 720.00
Independent Claims	8	-3	=	5	x	\$84.00	=	\$ 420.00
<input type="checkbox"/> Fee of _____ for the first filing of one or more multiple dependent claims per application								\$
<input type="checkbox"/> Fee for Request for Extension of Time								\$


Please make the following charges to Deposit Account 19-2386:

- ☒ Total fee for filing the patent application in the amount of \$ 1,880.00
☒ The Commissioner is hereby authorized to charge any additional fees which may be required, or credit any overpayment to Deposit Account 19-2386.

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Respectfully submitted,


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 J106 U.S. PTO
 10/038714
 01/02/02


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